



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC12DN20NS3 G		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA000862670						
<b>Package</b>		PG-TDSON-8-5		<b>Weight*</b>		116.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.374	1.18	1.18	11787	11787
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		422	
	inorganic material	phosphorus	7723-14-0	0.015	0.01		126	
	non noble metal	copper	7440-50-8	49.082	42.10	42.15	421075	421623
wire	non noble metal	copper	7440-50-8	0.071	0.06	0.06	606	606
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		695	
	plastics	epoxy resin	-	5.753	4.94		49352	
	inorganic material	silicondioxide	60676-86-0	34.678	29.75	34.76	297501	347548
leadfinish	non noble metal	tin	7440-31-5	1.452	1.25	1.25	12454	12454
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1420	1420
solder	non noble metal	tin	7440-31-5	0.030	0.03		261	
	noble metal	silver	7440-22-4	0.038	0.03		327	
	non noble metal	lead	7439-92-1	1.455	1.25	1.31	12485	13073
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		191	
	non noble metal	copper	7440-50-8	22.292	19.12	19.15	191241	191489
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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